

WHAT IS CLAIMED IS:

1. A packaging structure integrating passive devices, comprising:

a leadframe, wherein the leadframe includes a plurality of first leads defining a chip-bonding region, a plurality of second leads extending and terminating in a plurality of contact pads within the chip-bonding region, and a die pad located in the chip-bonding region;

a chip bonded onto the die pad;

at least a passive device mounted between and connected to the contact pads;

a plurality of bonding wires electrically connecting the chip, the passive device, and the first and second leads to one another; and

an encapsulant material encapsulating the chip, the passive device, and the bonding wires.

2. The packaging structure of claim 1, wherein the passive device connects the contact pads by surface mount technology.

3. The packaging structure of claim 1, wherein a portion of each first and second lead extends out of the encapsulant material.

4. A quad flat package including the packaging structure of claim 1.

5. A plastic chip carrier package including the packaging structure of claim 1.

6. The packaging structure of claim 1, further including an adhesive tape disposed on bottom surfaces of the contact pads to improve a rigidity of the contact pads.

7. The packaging structure of claim 1, wherein the passive device is a resistor, a capacitor or an inductor.

8. A leadframe structure suitable for use in a chip packaging structure, the leadframe structure comprising:

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a plurality of first leads defining a chip-bonding region in the leadframe structure;
a plurality of second leads extending and terminating in a plurality of contact pads
within the chip-bonding region; and
a die pad arranged in the chip-bonding region.

5 9. The leadframe structure of claim 8, further including an adhesive tape bonded
to bottom surfaces of the contact pads to improve a rigidity of the contact pads.

10 10. A packaging structure integrating passive devices, comprising:
a leadframe, wherein the leadframe includes a plurality of first leads defining a
chip-bonding region, a plurality of second leads extending and terminating in a plurality
of contact pads within the chip-bonding region, and a die pad located in the chip-bonding
region;

15 an adhesive tape bonded to bottom surfaces of the contact pads;
a chip bonded onto the die pad;
at least a passive device mounted between and connected to the contact pads;
a plurality of bonding wires electrically connecting the chip, the passive device,
and the leads to one another; and

an encapsulant material encapsulating the chip, the passive device, and the
bonding wires.

20 11. The packaging structure of claim 10, wherein a portion of each first and
second lead extends out of the encapsulant material.

12. A quad flat package including the packaging structure of claim 10.

13. A plastic chip carrier package including the packaging structure of claim 10.

14. The packaging structure of claim 10, wherein the passive device is a resistor, a
capacitor or an inductor.

15. A leadframe structure suitable for use in a chip packaging structure, the leadframe structure comprising:

a plurality of first leads defining a chip-bonding region in the leadframe structure;

a plurality of second leads extending and terminating in a plurality of contact pads

5 within the chip-bonding region;

an adhesive tape bonded to bottom surfaces of the contact pads; and

a die pad arranged in the chip-bonding region.

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